

IN THE CLAIMS

1. to 16. (cancelled)

17. (original)           A           microelectronic           assembly  
comprising:

(a) a conductive element including a bottom wall and a plurality of side walls extending from said bottom wall so that said bottom wall and said side walls define a depression, said conductive element having one or more additional openings in at least one of said walls;

(b) a dielectric layer extending between said side walls, so that said dielectric layer and said conductive element substantially enclose an interior space within said depression and said one or more openings in said conductive element communicate with said interior space;

(c) a microelectronic element disposed within said interior space; and

(d) an encapsulant including an interior portion at least partially filling said interior space and at least partially surrounding said microelectronic element within said space, and an exterior portion exposed at an exterior surface of said conductive element in contact with said conductive element, said portions of said encapsulant being connected to one another through said one or more additional openings in said conductive element.

18. (original)           An assembly as claimed in claim 17 wherein said side walls define said one or more additional openings.

19. (original)           An assembly as claimed in claim 18 wherein said exterior portion at least partially covers one or more of said side walls.

20. (original) An assembly as claimed in claim 17 wherein said exterior portion of said encapsulant does not extend on said rear wall.

21. (original) An assembly as claimed in claim 20 wherein said dielectric element has one or more terminal structures thereon electrically connected to said microelectronic element and said exterior portion of said dielectric does not extend onto said terminal structures.

22. (original) An assembly as claimed in claim 17 wherein said side wall portions include a plurality of pillars spaced apart from one another, said one or more additional openings including spaces between adjacent ones of said pillars, said exterior portion of said encapsulant defining

23. (original) An assembly as claimed in claim 22 wherein said microelectronic element is adapted to operate at an operating frequency and said one or more additional openings have dimensions less than a wavelength of electromagnetic radiation at said operating frequency.